AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claim 1 (currently amended) An electroless plating method comprising the steps of:

preparing a substrate having an insulating body and a conductive pattern having electrodes formed on the insulating body;

adhering a catalytic metal serving as a catalyst of an electroless plating onto the insulating body and the conductive pattern;

coating selectively an oxidizing agent, which can oxidize the catalytic metal and make the catalytic metal in an inactive state to the electroless plating, on the catalytic metal in a space portion [[S]] between the electrodes of the conductive pattern;

and forming selectively a metal layer on the conductive pattern by the electroless plating, wherein the conductive pattern is arranged in a state such that the space portion between the electrodes of the conductive pattern has a plurality of different dimensions, and the oxidizing agent is ~~formed~~ selectively coated in portions, which are smaller than both a predetermined dimension and the space portion, out of the space portion between the electrodes of the conductive pattern.

Claim 2 (canceled).

Claim 3 (currently amended) An electroless plating method according to claim 1, wherein the step of ~~forming~~ selectively coating the oxidizing agent is carried out by an ink jet method.

Claim 4 (original) An electroless plating method according to claim 1, wherein the step of adhering the catalytic metal onto the insulating body and the conductive pattern includes the step of coating an activating solution containing ions of the catalytic metal to deposit the catalytic metal by an oxidation-reduction reaction.

Claims 5-6 (canceled).

Claim 7 (original) An electroless plating method according to claim 1, wherein the catalytic metal is palladium, and the metal layer formed by the electroless plating is a nickel layer or a copper layer.

Claim 8 (canceled).

Claim 9 (previously presented) An electroless plating method according to claim 11, wherein the protection film is a resist film or a polyimide film.

Claim 10 (previously presented) An electroless plating method according to claim 1, wherein the oxidizing agent is one of an H_2SO_4 solution and a mixed solution consisting of H_2SO_4 and HCl.

Claim 11 (currently amended) An electroless plating method comprising the steps of:

preparing a substrate having an insulating body and a conductive pattern having electrodes formed on the insulating body;

adhering a catalytic metal serving as a catalyst of an electroless plating onto the insulating body and the conductive pattern;

forming selectively a protection film on the catalytic metal in a space portion between the conductive pattern; and

forming selectively a metal layer on the conductive pattern by the electroless plating,

wherein the conductive pattern is arranged such that the space portion between electrodes of the conductive patterns has a plurality of different dimensions, and the protection film is formed selectively in portions, which are smaller than both a predetermined dimension and the space portion, out of the space portion between the electrodes of the conductive pattern.

Claim 12 (currently amended) An electroless plating method according to claim 1, wherein the oxidizing agent is ~~formed~~ selectively coated in the space portions which are ~~small~~ smaller than 30 μm.